H.ELE. Specifications for Approva

(8)

CUSTOMER

PRODUCT TYPE <u>Crystal Oscillator HSO221S</u>

NOMINAL FREQUENCY 22.118400MHz

H.ELE. SAMPLE O/N EOS-GC0180-1

H.ELE. P/N S2H022118F3CHC-T

RELEASE DATE 2016/12/13

VERSION ______00

MSL Level 01

GREEN PRODUCT ☑ Pb free **☑ RoHS Compliant**

☑ HF-Halogen free **☑** REACH Compliant

CUSTOMER P/N

APPLICATION & MODEL

APPROVED BY CUSTOMER

(DATE)

Harmony Electronics Corp.	
F. S. TSAI C. H. WENG U. F. CHEN (PREPARE)	Country of Origin: Taiwan Factory Thailand Factory China Factory

HARMONY ELECTRONICS CORPRATION

KAOHSIUNG TAIPEI THAILAND SHENZHEN SUZHOU



REV. No.	DATE	REASON	REVISE CONTENTS
0	2016/12/13	New	

HARMONY ELECTRONICS CORPRATION

KAOHSIUNG	TAIPEI	THAILAND	SHENZHEN	Suzhou



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Kaohsiung Taipei Thailand Shenzhen Suzhou



1. CRYSTAL OSCILLATOR SPECIFICATION

■ Electrical Specifications

Items	Cumbal	Е	lectrical Spe	C.	Unit	Condition	
items	Symbol	Min	Type	Max	Unit	Condition	
1. Output Frequency	(FL)	22.118400			MHz		
Frequency Stability	Δf/F	-30 - +30		ppm	@3.3±0.3V/-20~70°C		
Operating temp. range	Topr	-20	25	+70	°C		
Supply voltage	Vdd	3.0	3.3	3.6	V		
Pin #1 options				YES			
Output load		C-MC	OS CL =15p	F (Idd1, Id	dd2 test at N	No Load)	
Current consumption 1 (#1 pin: open or "H")	ldd1	-	-	7	mA		
Current consumption 2 (#1 pin: "L" level)	Idd2	-	-	0.01	mA		
Low level output voltage	Vol	-	-	0.1xVdd	V		
High level output voltage	Voh	0.9xVdd	1	-	V		
Symmetry	Duty	40	50	60	%		
Rise & Fall time	Tr & Tf	-	-	10	ns		
Low level input current	lil	-	-	10	uA	@3.3V/ 25±3°C	
High Level input current	lih	-	-	10	uA		
Low level input voltage	Vil	-	-	Vddx0.3	V		
High level input voltage	Vih	Vddx0.7	-	-	V		
Output disable time	Tplz	-	-	150	nsec		
Output enable time	Tpzl	-	-	10	msec		
Aging	-	-3	-	3	ppm/year		
Start-up time		-	-	10	ms		
Jitter, Phase	RMS(1-σ)	-	-	1	ps	12KHz~20MHz Frequency Band	

Note:

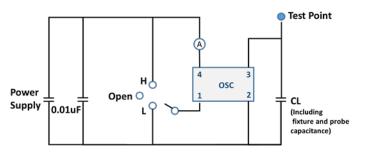
■ Absolute Maximum Ratings

Item	Symbol	Value	Unit
Vdd terminal voltage	Vdd	-0.5 ~ 4.0	V
Input terminal voltage	Vcont	-0.5 ~ Vdd+0.5	V
Output terminal voltage	Vout	-0.5 ~ Vdd+0.5	V
Output terminal current	lout	15	mA
Storage temp. range	Tstr	-55 ~ 12 5	deg.C

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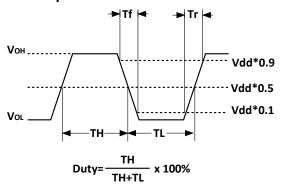
■TEST Circuit



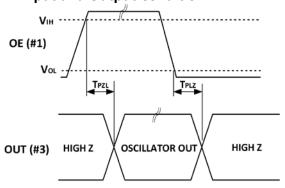
CL = Include jig & probe capacitance (Refer to 4)

Switch	Out term.
Н	Oscillation out
Open	Oscillation out
L	High Z

■ Output Wave Form

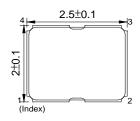


■ Input and Output Condition



2. DIMENSION



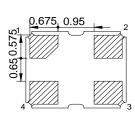


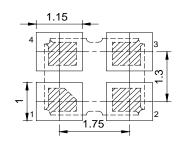


Unit: mm

BOTTOM VIEW

TOP VIEW Land Pattern Layout





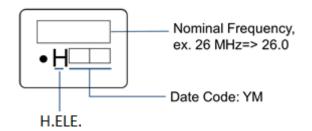
Connections
OE(Output Enable)
GND
Output
Vdd

^{*} Note: The Index mark was defined by the BASE suppliers.

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3. MARKING



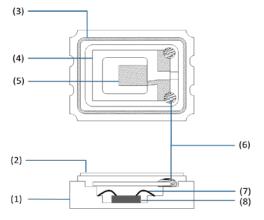
Note:

- 1. Laser marking.
- 2. Date Code:

V V	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019
Y= Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	0	1	2	3	4	5	6	7	8	9

M= Month	Jan.	Feb.	Mar.	Apr.	May.	Jun.	Jul.	Aug.	Sep.	Oct.	Nov.	Dec.
Code	Α	В	С	D	Е	F	G	Н	J	K	L	М

4. INSIDE STRUCTURE



Reference	drawing
Mererence	urawing

No.	Component	Material	Note
1	Base	Al_2O_3	
2	Lid	Fe- Ni -Co	
3	Kovar	Fe-Ni-Co	
4	Crystal Blank	SiO ₂	Rectangular At-Cut
5	Electrode		
6	Connective Adhesive		
7	Bonding Wire	Au	
8	IC	Si, Al	

※The use prohibition chemistry substance of Table 1 of DHE-0204-1 (HE-QA-24) is not included in this item.

5. HANDDLING SUGGESTION

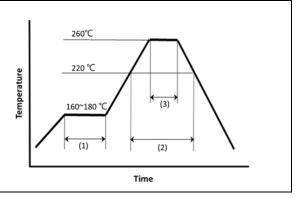
■ Reflow Condition

Please stay with our proposed reflow condition and do soldering 2 times max.

(1)	Preheat	160~1	L80deg.C	120 sec.
(2)	Primary heat	220	deg.C	100 sec.
(3)	Peak	260	deg.C	10 sec. Max.

Manual Solder iron (Example)

Bit temp.: 350°C max., Time: 3sec max., Each terminal solder a 1 time max.



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■ Mounting Conditions

Our products are suitable for most automated SMT processes. However, we strongly advise all our customers to conduct SMT sampling prior to mass production in order to make sure production processes will not affect the properties and specifications of our product. Seal welding and mounting procedures involving the use of ultra-sonic processes are not recommended and will affect and/or damage the internal properties of our product. Excessive shock during the mounting process will also affect the product and we strongly recommend setting SMT conditions to minimize such conditions.

If a possibility of the PCB being warped exists we strongly advise to ensure the degree of warping will not affect the product.

Please also ensure the operating characteristics and or soldering conditions are all within the specifications of use for our product.

Ultimately the worst case scenario of all the above will lead to cases of non-oscillation but other negative effects are also likely should our products be used in an inappropriate way. Please note such cases of misuse and its related quality issues are not included in our product warranty.

Cleansing Conditions

General cleaning solutions may be used to clean our products but we always recommend testing to be performed prior to mass production processes. Ultrasonic cleaning procedures are not recommended and we strongly advise other forms of cleansing to be evaluated first. Unsuitable cleansing may lead to a number of negative effects such as damage to the product surface, discoloration of the product, corrosion of the package, package contamination, illegible marking, etc. Please note cases of unadvised treatment and its related quality issues are not included in our product warranty.

■ Storage Conditions

Please ensure our products are preserved appropriately in their original packaging. Irregular environmental instances of moisture will affect our product's stability and may cause problems such as frequency instability, soldering ability and conditions, package defects, and other problems. It is essential to keep our products in a clean dust-free environment out of direct sunlight.

Our products' storage conditions should at least meet the following condition:

Environmental Temperature: + 40 degrees Celsius Maximum

Relative Humidity: 80% Maximum

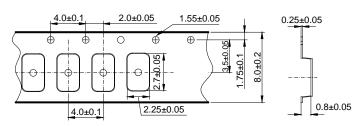
Please note storage instances which do not conform to our guidelines and the related quality issues produced as an outcome are not included in our product warranty.

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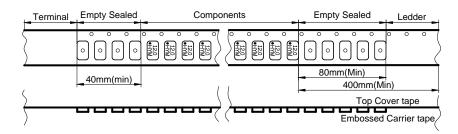


6. EMBOSS CARRIER TAPE AND REEL

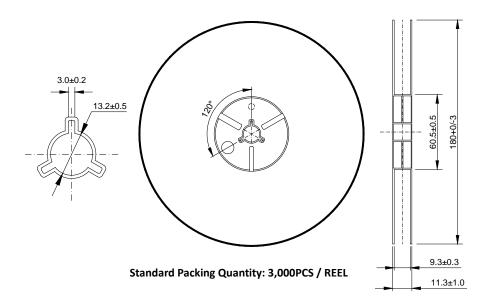
■ Carrier Tape



User Direction of feed



■ Reel



■ Material of The Tape

Таре	Material	
Carrier tape	PS Conductive	
Top tape	PET	

■ Joint of tape

The carrier-tape and top cover-tape should not be jointed.

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■ Release strength of cover tape

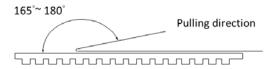
It has to between 0.1N to 0.7N under

following condition.

Pulling direction: 165° to 180°

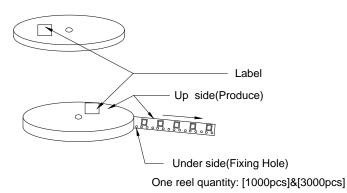
Speed: 300mm/min.

Otherwise unless specified.

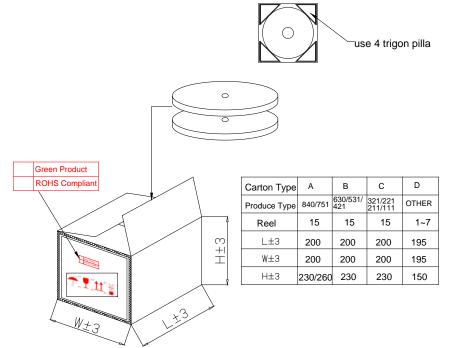


Other standards shall be based on JIS C 0806-1990.

7. PACKAGE







- ①Top and bottom with 2.3cm thickness foam-rubber cushion for protection.
- ②Carton's Q'TY:1~15 pcs.
- ③Carton Type=A,B,C use 4 trigon pillar to fasten the Reel.
- 4) Need to add 3 pages dry agent in each outer box.

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8. MECHANICAL PERFORMANCE

	Item	Test Methods	Specifications Code
1	Shock	Dropping from 50 cm height 3 times on 30mm Hard Wooden Board. Refer to: JIS C 60068-2-6	Α
2	Vibration	Frequency 10-55Hz, Sine Wave full amplitude of 0.8mm to X, Y and Z 3 axes, Duration of 2 hours to each axis. Refer to: MIL-HDBK-781A 6.5.2/ JIS C 60068-2-6	Α
3	Leakage Test	Leak Rate 1.0x10 ⁻⁹ Pa-m³/sec. Max. Measured by Helium leak detector.	
4	Solder ability	After applying ROSIN Flux, dipping in solder bath at 245deg.C +/-5deg.C for 3+/-0.5 sec. Refer to: JIS C 60068-2-20	В

9. ENVIRONMENT PERFORMANCE

ltem		Test Methods	Specifications Code
1	Resistance of Soldering Heat	Performing as the following reflow: 260°C 220°C 160°-180°C 100±20s	А
1	Humidity	Temperature 60° +/- 2° , RH 90~95%, Duration of 240 hours. Back to room temperature first, then in 1~2 hours, the component shall be checked. Refer to: JIS C 60068-2-3	А
2	Storage in Low Temperature	-40deg.C +/-2deg.C, Duration of 240 hours. Back to the room temperature first, then in 1~2 hours, the component shall be checked. Refer to: JIS C 60068-2-1	А
3	Storage in High Temperature	+85deg.C +/-2deg.C, Duration of 240 hours. Back to the room temperature first, then in 1~2 hours, the component shall be checked. Refer to: JIS C 60068-2-2	А
4	Temperature cycles	-30deg.C +/-2deg.C (30min) \leftrightarrow +85deg.C +/-2deg.C (30min) 25 cycles. And Temperature Increasing/reducing time $<$ 3mins. Back to the room temperature first, then in 1~2 hours, the component shall be checked. Refer to: JIS C 0025	Α

Specifications code	Specifications
Α	Frequency variation shall be within +/-5ppm and equivalent resistance shall be within
	+/-15% or 2Ω
В	More than 90% of lead shall be covered by new solder.

HARMONY ELECTRONICS CORPRATION

FACTORY LOCATION HEAD OFFICE/TAIWAN FACTORY

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CHINA FACTORY

JU YUAN INDUSTRIAL PARK, QIAO TANG ROAD, TANG WEI COMMUNITY, FUYONG, BAOAN DISTRICT, SHEN ZHEN CITY, CHINA (Post Code:518103).

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